	03-11-2002	Docket	No.:500.41293X00
FORM PTO: 1595 NRD REC 1-31-92 2127/02		(EET	U.S. DEPARTMENT OF COMMERC Patent and Trademark Offic
To the Honorable Commissioner of Patents and Trac	102009972	.ned original doc	cuments or copy thereof.
 Name of conveying party(ies): Tasao SOGA, Toshiharu ISHIDA, Kazuma MIUF Hanae HATA, Masahide OKAMOTO, Tetsuya NAKATSUKA 	A, Name: Hita		g party(ies): 1gadai 4-chome, Chiyoda-ku 0
Additional name(s) of conveying party(ies) attached? Yes 3. Nature of conveyance: Assignment Merger Security Agreement Change of Name Other	City: To Country:	okyo Japan] j⊂971 U.S. PT 10/083543
	Additional nan	Additional name(s) & address(es) attached? 🗌 Yes 🕱 No	
If this document is being filed together with a new A. Patent Application No.(s) 10083543		tent No.(s)	on is: January 21,28, 2002
5. Name and address of party to whom corresponden concerning document should be mailed:			
Name: ANTONELLI, TERRY, STOUT & KRA	US, LLP 7. Total fee (3	7. Total fee (37 CFR 3.41)\$40.00	
Internal Address:	Enclose	ficiencies may be	charged to deposit account to deposit account
1200 Month Seventeenth Street		8. Deposit account number: 01-2135	
Street Address: 1300 North Seventeenth Street Suite 1800		(Attach duplicate copy of this page if paying by deposit account)	
City: Arlington State: VA Zip: 22209 DO NOT USE THIS SPACE			
9. Statement and signature. To the best of my knowledge and belief, the of the original document. William I. Solomon Name of Person Signing Attorney Registration No. 28,565 Total number of pages including cover sheet, attachments, and OMB No. 0651-0011 (exp. 4/94)	<u>lliam</u> ature	e and correct and	any attached copy is a true copy <u>February 27, 2002</u> Date
03/05/2002 STEUMEL1 00000060 10083543			
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PATENT REEL: 012642 FRAME: 0932

ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

Product using Zn-AI alloy solder

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully

and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

Date Signed INVENTOR(S) (署名日) (発明者フルネームサイン) 2002 Jasao Saga Jospiharu Ispida 2002 2002 1/21/2002 Hata masahide akamoto Tetenya Ra 1/21/2002 6) _____ 7) 8) 9) _____